



Texas Instruments Incorporated

Texas Instruments Incorporated Conflict Minerals Update

February 20, 2012

Dear TI Customer,

We have received several inquiries from our customers in response to the Conflict Minerals issue addressed in Section 1502 of the **Dodd-Frank Wall Street Reform and Consumer Protection Act** that was passed by the US Congress in July 2010. Although the final regulations have still not been issued by the SEC, TI has been working with the EICC/GeSI Extractives work group and our direct suppliers to begin tracing minerals back to their origin in order to ensure responsible sourcing.

TI uses Tantalum, Tin, Tungsten, and Gold to manufacture semiconductor devices. Each of these metals has specific electrical properties which are necessary for the function of our products.

TI does not purchase these metals directly from smelters or mines, so we must rely on the source information provided by our suppliers. TI is requesting this information using the standardized **EICC/GeSI Conflict Minerals Reporting Template** that traces the metals back through the supply chain. The information provided thus far is incomplete, as the supply chain is still working through the process with their suppliers and sub-suppliers. We have a preliminary report of the smelters and mines in TI's supply chain based on the information provided thus far. We will continue to improve this information and provide periodic updates as more data becomes available.

TI supports industry initiatives such as the Conflict Free Smelter (CFS) program to validate responsible and sustainable sources. As the validated smelter lists become available, TI will request suppliers to source metals from the listed smelters.

In the meanwhile if you have any questions, please contact TI's Conflict Minerals Compliance Team at conflictmineralsti@list.ti.com.

Thank you for your patience in this matter. We look forward to our continued partnership.

Sincerely,

A handwritten signature in black ink, appearing to read 'Rob Simpson', written over a white rectangular area.

Rob Simpson
Vice President, Worldwide Procurement and Logistics
Texas Instruments

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